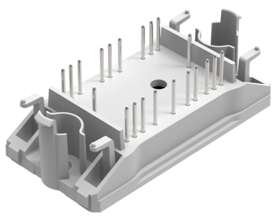
V23990-P860-F49-PM
datasheet

*flow*PACK 0	1200 V / 35 A

Features

- Trench Fieldstop IGBT4 technology
- Compact and low inductance design
- Built-in NTC

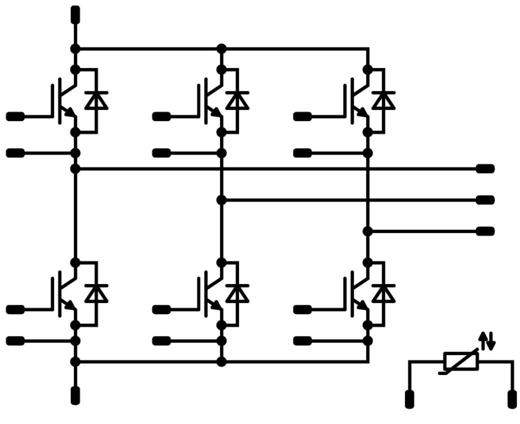
flow 0 17 mm housing



Target applications

- Motor Drives
- Power Generation
- UPS

Schematic



Types

- V23990-P860-F49-PM

Maximum Ratings

T_j = 25 °C, unless otherwise specified

Parameter	Symbol	Conditions		Value	Unit
Inverter Switch					
Collector-emitter voltage	V_{CES}			1200	V
Collector current (DC current)	I_C	$T_j = T_{jmax}$	T_s = 80 °C	39	A
Repetitive peak collector current	I_{CRM}	t_p limited by T_{jmax}		105	A
Total power dissipation	P_{tot}	$T_j = T_{jmax}$	T_s = 80 °C	101	W
Gate-emitter voltage	V_{GES}			±20	V
Short circuit ratings	t_{SC}	V_{GE} = 15 V, V_{CC} = 800 V	T_j = 150 °C	10	μs
Maximum junction temperature	T_{jmax}			175	°C
Inverter Diode					
Peak repetitive reverse voltage	V_{RRM}			1200	V
Forward current (DC current)	I_F	$T_j = T_{jmax}$	T_s = 80 °C	42	A
Repetitive peak forward current	I_{FRM}	t_p limited by T_{jmax}		70	A
Total power dissipation	P_{tot}	$T_j = T_{jmax}$	T_s = 80 °C	80	W
Maximum junction temperature	T_{jmax}			175	°C
Module Properties					
Thermal Properties					
Storage temperature	T_{stg}			-40…+125	°C
Operation temperature under switching condition	T_{jop}			-40…+(T_{jmax} - 25)	°C
Isolation Properties					
Isolation voltage	V_{isol}	DC Test Voltage*	t_p = 2 s	6000	V
Isolation voltage	V_{isol}	AC Voltage	t_p = 1 min	2500	V
Creepage distance				>12,7	mm
Clearance				>12,7	mm
Comparative Tracking Index	CTI			≥ 200	

*100 % tested in production

Characteristic Values

Parameter	Symbol	Conditions					Values			Unit
			V_{GE} [V] V_{GS} [V]	V_{CE} [V] V_{DS} [V] V_F [V]	I_C [A] I_D [A] I_F [A]	T_j [°C]	Min	Typ	Max	
Inverter Switch										
Static										
Gate-emitter threshold voltage	$V_{GE(th)}$	$V_{CE} = V_{GE}$			0,0012	25	5,3	5,8	6,3	V
Collector-emitter saturation voltage	V_{CEsat}		15		35	25 150	1,58	1,9 2,33	2,07[(1)]	V
Collector-emitter cut-off current	I_{CES}		0	1200		25			5	µA
Gate-emitter leakage current	I_{GES}		20	0		25			120	nA
Internal gate resistance	r_g							None		Ω
Input capacitance	C_{ies}	f = 1 Mhz	0	25		25		2000		pF
Reverse transfer capacitance	C_{res}							70		pF
Gate charge	Q_g		15		0	25		270		nC
Thermal										
Thermal resistance junction to sink [(2)]	$R_{th(j-s)}$	λ_{paste} = 3,4 W/mK (PSX)						0,94		K/W
Dynamic										
Turn-on delay time	$t_{d(on)}$	R_{gon} = 16 Ω R_{goff} = 16 Ω	±15	600	35	25 150		85,4 88,6		ns
Rise time	t_r					25 150		21,6 25,8		ns
Turn-off delay time	$t_{d(off)}$					25 150		199 258,8		ns
Fall time	t_f					25 150		73,35 115,18		ns
Turn-on energy (per pulse)	E_{on}	Q_{rFWD}=3,79 µC Q_{rFWD}=7 µC				25 150		2,48 3,71		mWs
Turn-off energy (per pulse)	E_{off}					25 150		1,84 2,91		mWs

Characteristic Values

Parameter	Symbol	Conditions	V_{GE} [V] / V_{GS} [V]	V_{CE} [V] / V_{DS} [V] / V_F [V]	I_C [A] / I_D [A] / I_F [A]	T_j [°C]	Min	Typ	Max	Unit
Inverter Diode										
Static										
Forward voltage	V_F				35	25 150	1,35	1,79 1,76	2,05(1)	V
Reverse leakage current	I_R	V_r = 1200 V				25			7,7	µA
Thermal										
Thermal resistance junction to sink (2)	$R_{th(j-s)}$	λ_{paste} = 3,4 W/mK (PSX)						1,19		K/W
Dynamic										
Peak recovery current	I_{RRM}	d*i*/d*t*=1463 A/µs d*i*/d*t*=1493 A/µs	±15	600	35	25 150		30,39 34,47		A
Reverse recovery time	t_{rr}					25 150		298,4 492,81		ns
Recovered charge	Q_r					25 150		3,79 7		µC
Reverse recovered energy	E_{rec}					25 150		1,48 2,81		mWs
Peak rate of fall of recovery current	$(di_{rf}/dt)_{max}$					25 150		121,56 104,89		A/µs

Characteristic Values

Parameter	Symbol	Conditions					Values			Unit
			V_{GE} [V] V_{GS} [V]	V_{CE} [V] V_{DS} [V] V_F [V]	I_C [A] I_D [A] I_F [A]	T_j [°C]	Min	Typ	Max	
Thermistor										
Static										
Rated resistance	R					25		22		kΩ
Deviation of R_{100}	$\Delta_{R/R}$	R_{100} = 1484 Ω				100	-5		5	%
Power dissipation	P							5		mW
Power dissipation constant	d					25		1,5		mW/K
B-value	$B_{(25/50)}$	Tol. ±1 %						3962		K
B-value	$B_{(25/100)}$	Tol. ±1 %						4000		K
Vincotech Thermistor Reference									I	

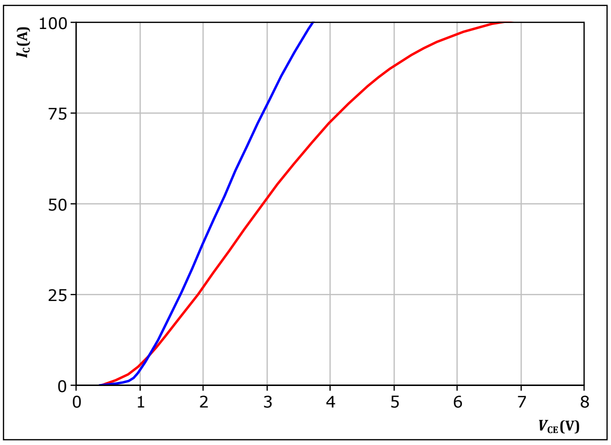
(1) Value at chip level
(2) Only valid with pre-applied Vincotech thermal interface material.

Inverter Switch Characteristics

figure 1. **IGBT**

Typical output characteristics

$I_C = f(V_{CE})$

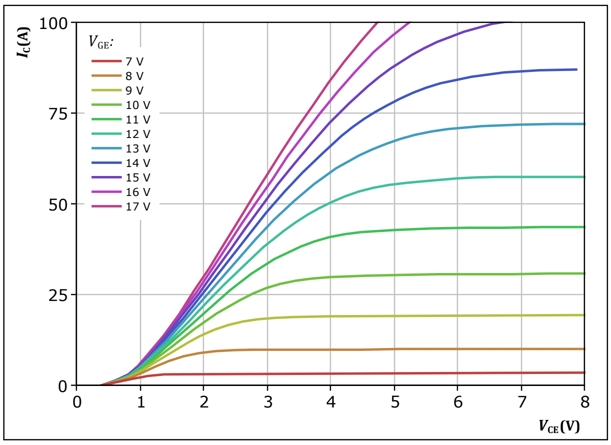


t_p =	250	μs	T_j:	25 °C
V_{GE} =	15	V		150 °C

figure 2. **IGBT**

Typical output characteristics

$I_C = f(V_{CE})$



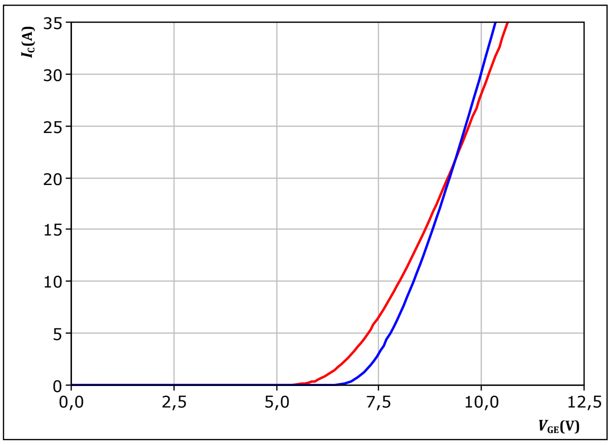
t_p =	250	μs
T_j =	150	°C

V_{GE} from 7 V to 17 V in steps of 1 V

figure 3. **IGBT**

Typical transfer characteristics

$I_C = f(V_{GE})$

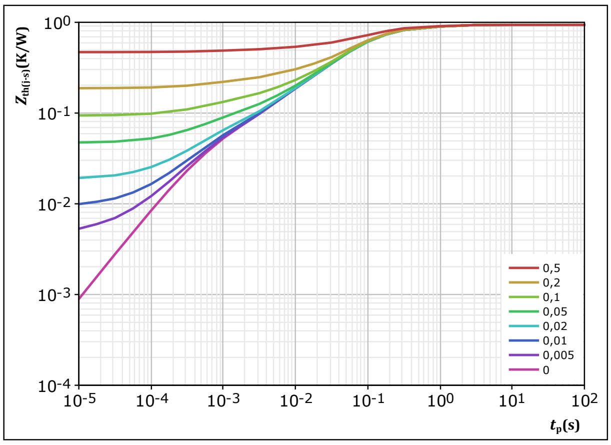


t_p =	250	μs	T_j:	25 °C
V_{CE} =	10	V		150 °C

figure 4. **IGBT**

Transient thermal impedance as a function of pulse width

$Z_{th(j\text{-}s)} = f(t_p)$



D =	t_p / T	
$R_{th(j\text{-}s)}$ =	0,938	K/W

IGBT thermal model values

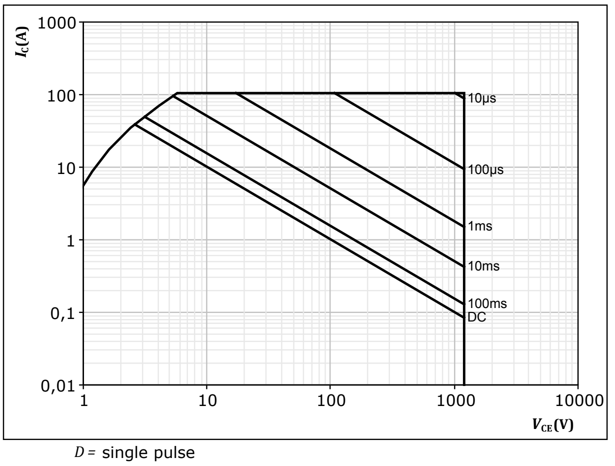
R (K/W)	τ (s)
1,15E-01	9,47E-01
4,15E-01	1,24E-01
2,99E-01	4,81E-02
7,22E-02	5,86E-03
3,82E-02	5,62E-04

Inverter Switch Characteristics

figure 5. **IGBT**

Safe operating area

I_C = f(V_{CE})



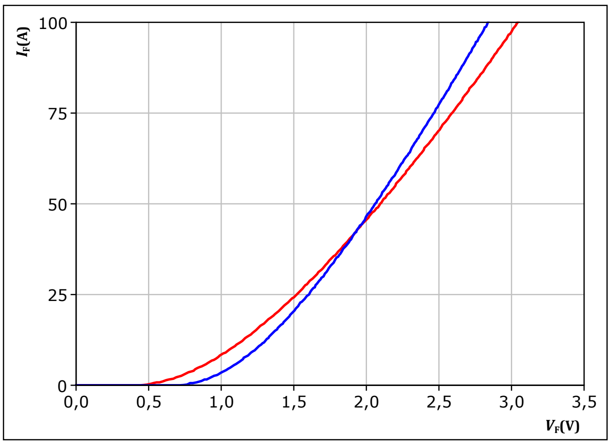
D =	single pulse	
T_s =	80	°C
V_{GE} =	15	V
T_j =	T_{jmax}	

Inverter Diode Characteristics

figure 6. **FWD**

Typical forward characteristics

$I_F = f(V_F)$



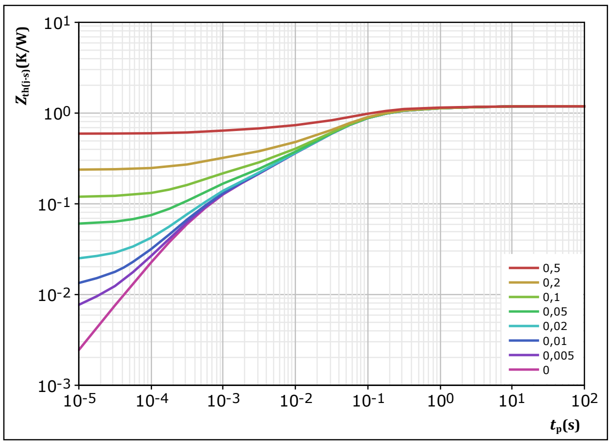
t_p = 250 µs

T_j: 25 °C, 150 °C

figure 7. **FWD**

Transient thermal impedance as a function of pulse width

$Z_{th(j-s)} = f(t_p)$



$D = t_p / T$

$R_{th(j-s)}$ = 1,187 K/W

FWD thermal model values

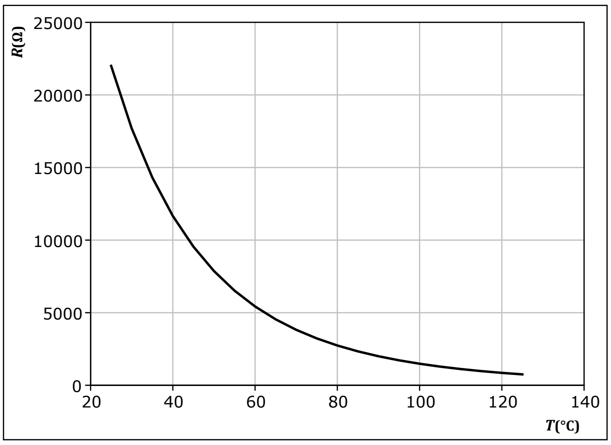
R (K/W)	τ (s)
6,30E-02	2,93E+00
1,30E-01	4,06E-01
5,50E-01	7,36E-02
2,26E-01	2,16E-02
1,15E-01	4,46E-03
9,49E-02	5,82E-04
8,50E-03	2,11E-04

Thermistor Characteristics

figure 8.	Thermistor

Typical NTC characteristic as function of temperature

R_T = f(T)

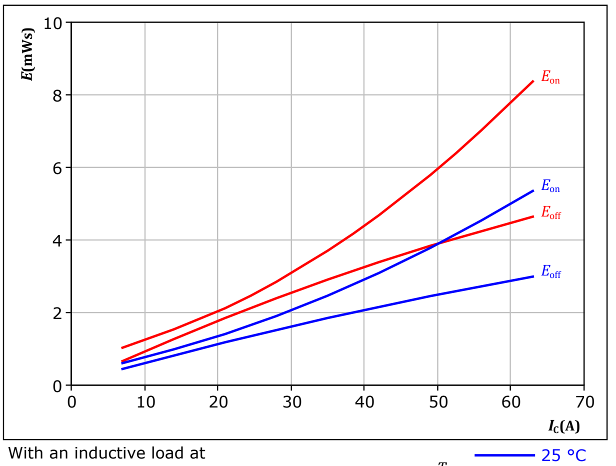


Inverter Switching Characteristics

figure 9. **IGBT**

Typical switching energy losses as a function of collector current

$E = f(I_C)$



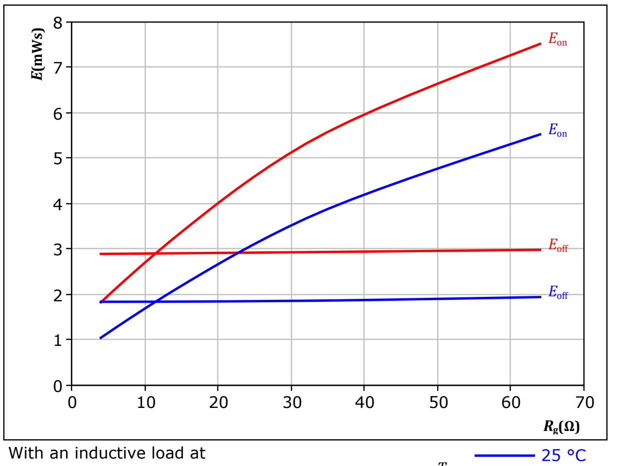
With an inductive load at

V_{CE} =	600	V	T_j:	25 °C
V_{GE} =	±15	V		150 °C
R_{gon} =	16	Ω		
R_{goff} =	16	Ω		

figure 10. **IGBT**

Typical switching energy losses as a function of gate resistor

$E = f(R_g)$



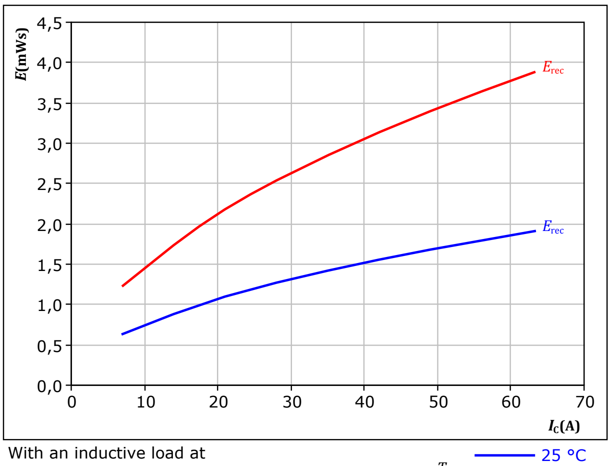
With an inductive load at

V_{CE} =	600	V	T_j:	25 °C
V_{GE} =	±15	V		150 °C
I_C =	35	A		

figure 11. **FWD**

Typical reverse recovered energy loss as a function of collector current

$E_{rec} = f(I_C)$



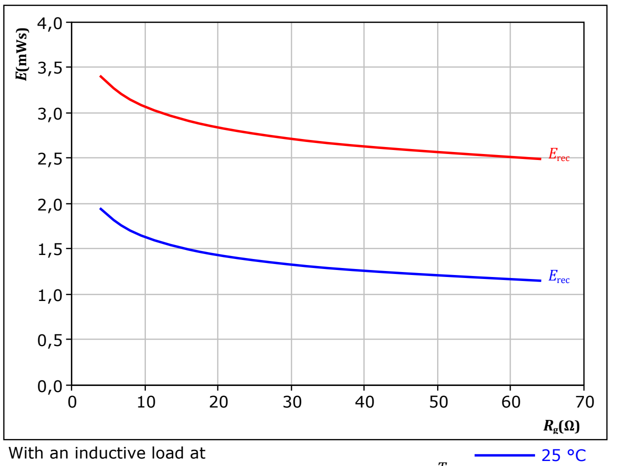
With an inductive load at

V_{CE} =	600	V	T_j:	25 °C
V_{GE} =	±15	V		150 °C
R_{gon} =	16	Ω		

figure 12. **FWD**

Typical reverse recovered energy loss as a function of gate resistor

$E_{rec} = f(R_g)$



With an inductive load at

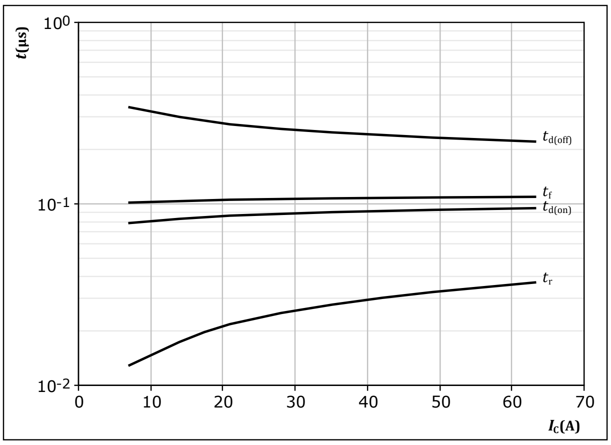
V_{CE} =	600	V	T_j:	25 °C
V_{GE} =	±15	V		150 °C
I_C =	35	A		

Inverter Switching Characteristics

figure 13. **IGBT**

Typical switching times as a function of collector current

$t = f(I_C)$



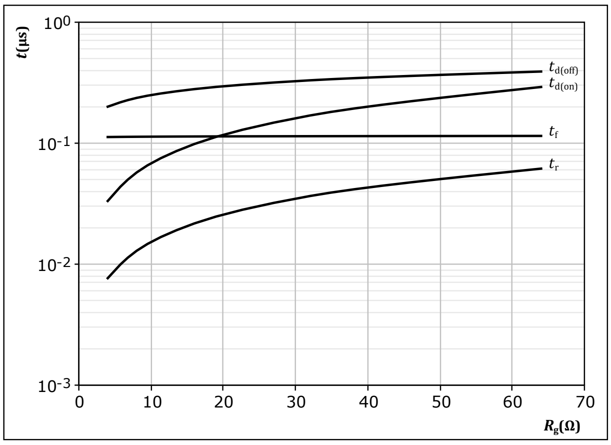
With an inductive load at

T_j =	150	°C
V_{CE} =	600	V
V_{GE} =	±15	V
R_{gon} =	16	Ω
R_{goff} =	16	Ω

figure 14. **IGBT**

Typical switching times as a function of gate resistor

$t = f(R_g)$



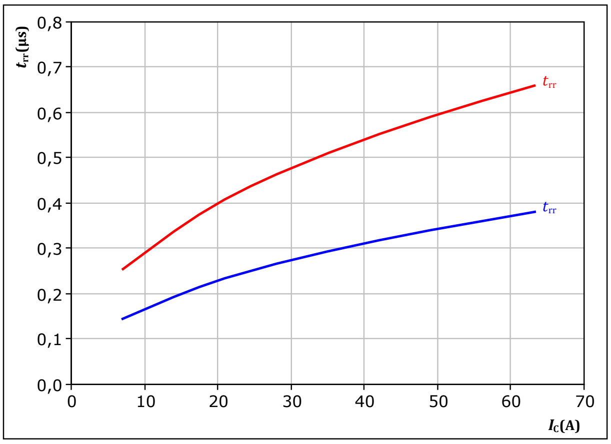
With an inductive load at

T_j =	150	°C
V_{CE} =	600	V
V_{GE} =	±15	V
I_C =	35	A

figure 15. **FWD**

Typical reverse recovery time as a function of collector current

$t_{rr} = f(I_C)$



With an inductive load at

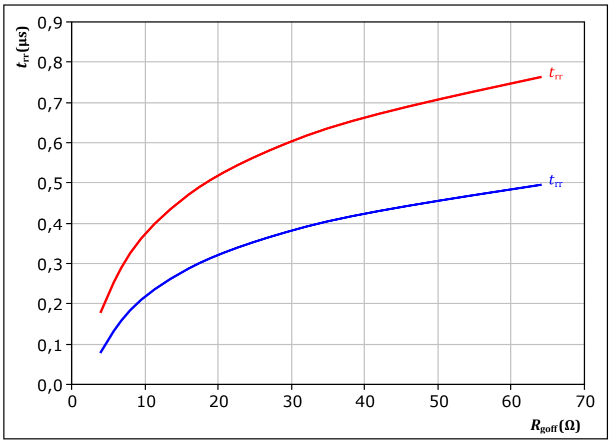
V_{CE} =	600	V
V_{GE} =	±15	V
R_{gon} =	16	Ω

T_j: 25 °C, 150 °C

figure 16. **FWD**

Typical reverse recovery time as a function of IGBT turn off gate resistor

$t_{rr} = f(R_{goff})$



With an inductive load at

V_{CE} =	600	V
V_{GE} =	±15	V
I_C =	35	A

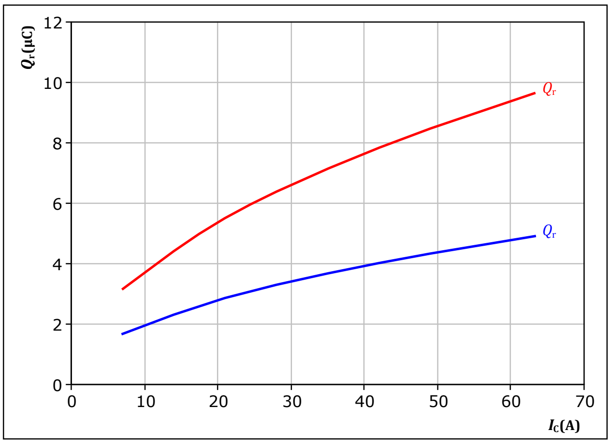
T_j: 25 °C, 150 °C

Inverter Switching Characteristics

figure 17. FWD

Typical recovered charge as a function of collector current

Q_r = f(I_C)



With an inductive load at

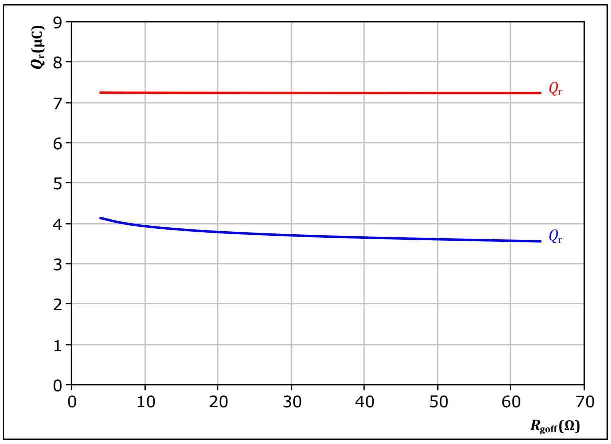
T_j: 25 °C / 150 °C

V_{CE} =	600	V
V_{GE} =	±15	V
R_{gon} =	16	Ω

figure 18. FWD

Typical recovered charge as a function of turn off gate resistor

Q_r = f(R_{goff})



With an inductive load at

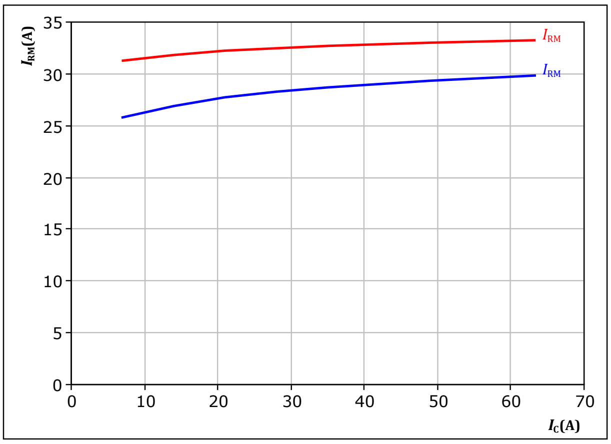
T_j: 25 °C / 150 °C

V_{CE} =	600	V
V_{GE} =	±15	V
I_C =	35	A

figure 19. FWD

Typical peak reverse recovery current as a function of collector current

I_{RM} = f(I_C)



With an inductive load at

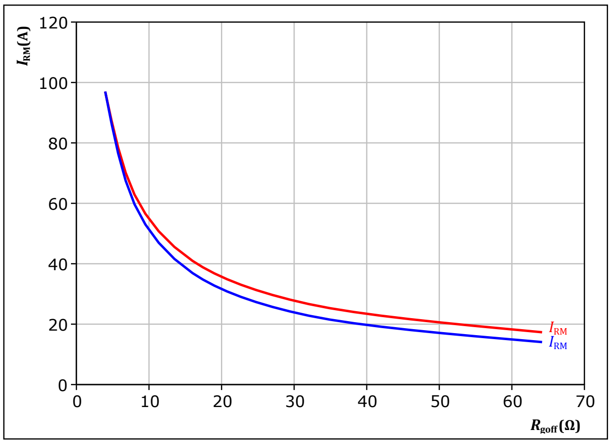
T_j: 25 °C / 150 °C

V_{CE} =	600	V
V_{GE} =	±15	V
R_{gon} =	16	Ω

figure 20. FWD

Typical peak reverse recovery current as a function of turn off gate resistor

I_{RM} = f(R_{goff})



With an inductive load at

T_j: 25 °C / 150 °C

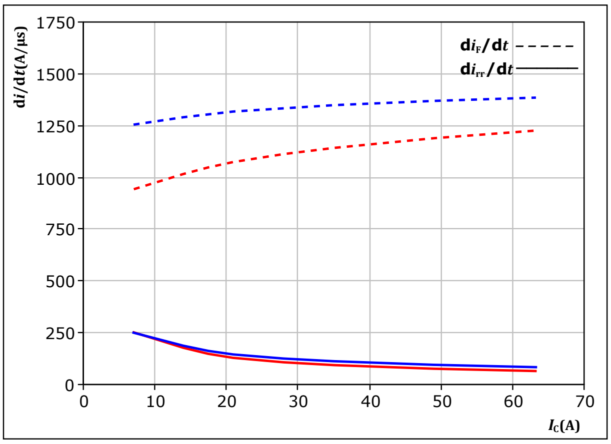
V_{CE} =	600	V
V_{GE} =	±15	V
I_C =	35	A

Inverter Switching Characteristics

figure 21. **FWD**

Typical rate of fall of forward and reverse recovery current as a function of collector current

$di_F/dt,\ di_{rr}/dt = f(\ I_C)$



With an inductive load at

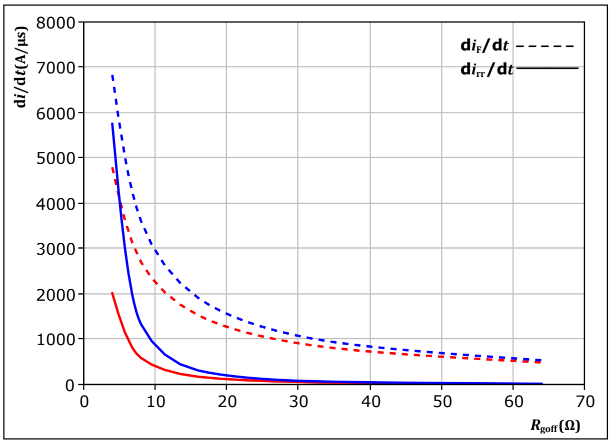
T_j: 25 °C, 150 °C

V_{CE} =	600	V
V_{GE} =	±15	V
R_{gon} =	16	Ω

figure 22. **FWD**

Typical rate of fall of forward and reverse recovery current as a function of turn off gate resistor

$di_F/dt,\ di_{rr}/dt = f(\ R_{goff})$



With an inductive load at

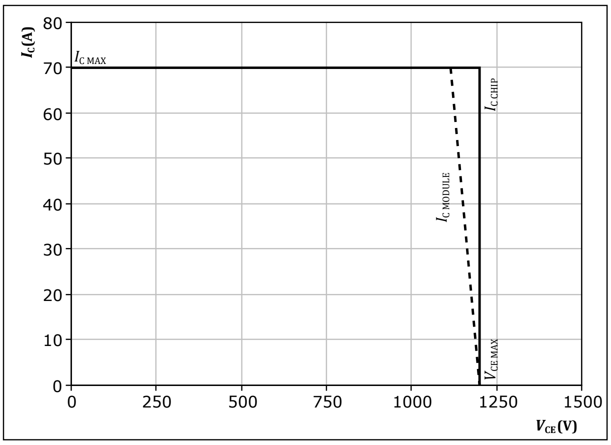
T_j: 25 °C, 150 °C

V_{CE} =	600	V
V_{GE} =	±15	V
I_C =	35	A

figure 23. **IGBT**

Reverse bias safe operating area

$I_C = f(\ V_{CE})$



At	T_j =	150	°C
	R_{gon} =	16	Ω
	R_{goff} =	16	Ω

Inverter Switching Definitions

figure 24. **IGBT**

Turn-off Switching Waveforms & definition of t_{doff}, t_{Eoff} (t_{tEoff} **= integrating time for** E_{off})

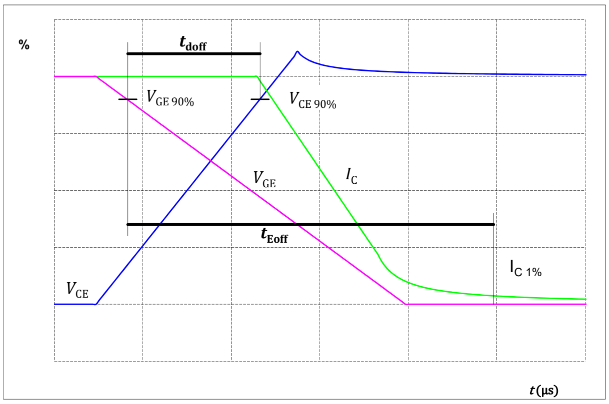


figure 25. **IGBT**

Turn-on Switching Waveforms & definition of t_{don}, t_{Eon} (t_{Eon} **= integrating time for** E_{on})

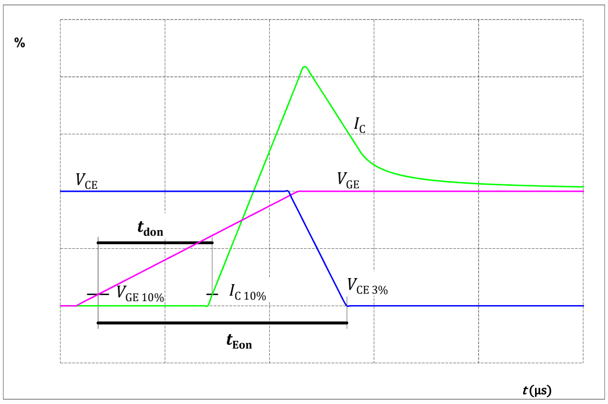


figure 26. **IGBT**

Turn-off Switching Waveforms & definition of t_f

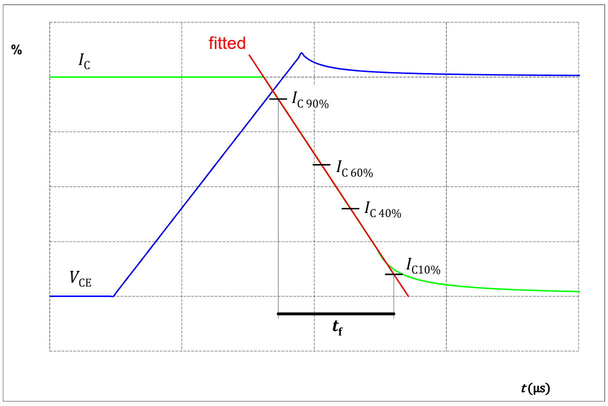
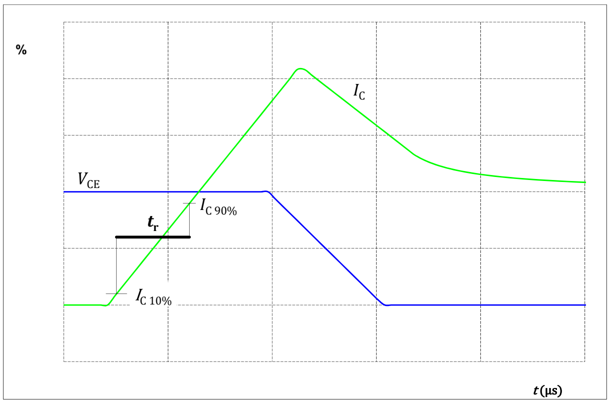


figure 27. **IGBT**

Turn-on Switching Waveforms & definition of t_r



Inverter Switching Definitions

figure 28. **FWD**

Turn-off Switching Waveforms & definition of t_{rr}

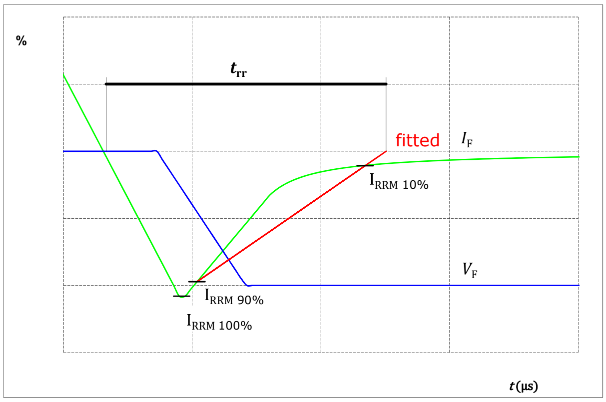
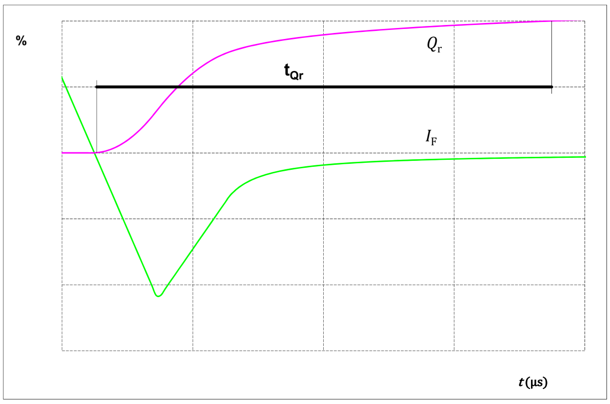


figure 29. **FWD**

Turn-on Switching Waveforms & definition of t_{Qr} **(**t_{Qr} **= integrating time for** Q_r**)**



V23990-P860-F49-PM
datasheet

Ordering Code

Version	Ordering Code
Without thermal paste	V23990-P860-F49-PM
With thermal paste (5,2 W/mK, PTM6000HV)	V23990-P860-F49-/7/-PM
With thermal paste (3,4 W/mK, PSX-P7)	V23990-P860-F49-/3/-PM

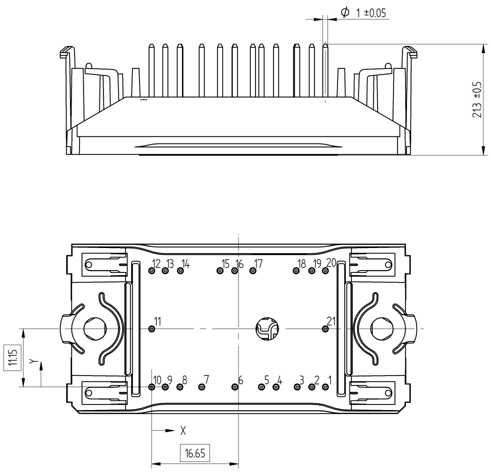
Marking

Text	**VIN**	**Date code**	**Type&Ver**	**UL**	**Lot**	**Serial**
	VIN	WWYY	TTTTTTTVV	UL	LLLLL	SSSS
Datamatrix	**Type&Ver**	**Lot number**	**Serial**	**Date code**		
	TTTTTTTVV	LLLLL	SSSS	WWYY		

Outline

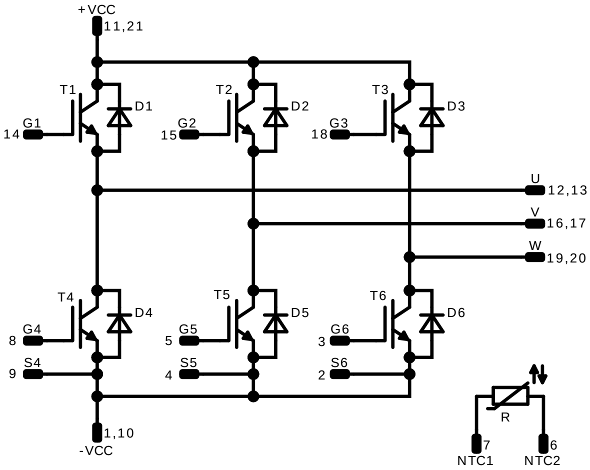
Pin table [mm]

Pin	X	Y	Function
1	33,3	0	-Vcc
2	30,7	0	S6
3	27,9	0	G6
4	23,85	0	S5
5	21,05	0	G5
6	15,95	0	NTC2
7	9,6	0	NTC1
8	5,4	0	G4
9	2,6	0	S4
10	0	0	-Vcc
11	0	11,15	+Vcc
12	0	22,3	U
13	2,6	22,3	U
14	5,5	22,3	G1
15	13,1	22,3	G2
16	15,9	22,3	V
17	19,4	22,3	V
18	27,7	22,3	G3
19	30,7	22,3	W
20	33,3	22,3	W
21	33,3	11,15	+Vcc



Tolerance of pinpositions: ±0,5mm at the end of pins
Dimension of coordinate axis is only offset without tolerance

Pinout



Identification

ID	Component	Voltage	Current	Function	Comment
T4, T1, T5, T2, T6, T3	IGBT	1200 V	35 A	Inverter Switch	
D1, D4, D2, D5, D3, D6	FWD	1200 V	35 A	Inverter Diode	
R	NTC			Thermistor	

Packaging instruction				
Standard packaging quantity (SPQ) 135	>SPQ	Standard	<SPQ	Sample

Handling instruction
Handling instructions for *flow* 0 packages see vincotech.com website.

Package data
Package data for *flow* 0 packages see vincotech.com website.

Vincotech thermistor reference
See Vincotech thermistor reference table at vincotech.com website.

UL recognition and file number
This device is certified according to UL 1557 standard, UL file number E192116. For more information see vincotech.com website.

Document No.:	Date:	Modification:	Pages
V23990-P860-F49-PM-D5-14	10 Sep. 2021	Introduce Rth values with PSX-P7 TIM Separate datasheet for 17 mm housing solder pin version New datasheet format, module is unchanged	